

## C1812C104K2TACTU

Aliases (C1812C104K2TAC7800) SMD Comm X8G HT150C, Ceramic, 0.1 uF, 10%, 200 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 1812, 2.3 mm



General Information		
Series	SMD Comm X8G HT150C	
Style	SMD Chip	
Description	SMD, MLCC, High Temperature, Ultra-Stable	
Features	High Temperature, Ultra-Stable	
RoHS	Yes	
Termination	Tin	
Marking	No	
AEC-Q200	No	
Typical Component Weight	87 mg	
Shelf Life	78 Weeks	
MSL	1	

Dimensions	
Chip Size	1812
L	4.5mm +/-0.3mm
W	3.2mm +/-0.3mm
Т	2mm +/-0.20mm
S	2.3mm MIN
В	0.6mm +/-0.35mm

Т	2mm +/-0.20mm
S	2.3mm MIN
В	0.6mm +/-0.35mm
Packaging Specifications	

Specifications	
Capacitance	0.1 uF
Measurement Condition	1 kHz 1.0Vrms
Tolerance	10%
Voltage DC	200 VDC
Dielectric Withstanding Voltage	500 VDC
Temperature Range	-55/+150°C
Temp. Coefficient	X8G
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
Dissipation Factor	0.1% 1 kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	10 GOhms

		Capacitance Change with	30 ppi11/C, ikmz i.t
Packaging	T&R, 180mm, Plastic Tape	Reference to +25°C and 0 VDC Applied (TCC)	, .
Packaging Quantity 50	500	11 \ ,	
		Dissipation Factor	0.1% 1 kHz 1.0Vrms
		Aging Rate	0% Loss/Decade I

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